



Intel[®] 440LX AGPset

Design Guide Update

August 1998

Order Number: 290642-001



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Revision History

Date of Revision	Document Name	Description
August 1998	001	Initial Release

Preface

This document is an update to the following document:

Intel Pentium® II processor/440LX AGPset Design Guide Rev 1.0, April 1998, order number 297651-001.

References may also be made to the following documents: Intel 440LX AGPset: 82443LX (PAC) data sheet section and the 82371AB (PIIX4) data sheet section of the Platform Components databook, order number 296467-009.

It is intended for hardware system manufacturers and software developers of applications, operating systems, or tools. This design guide is primarily targeted at the PC market segment and was first published in 1998. Those using this design guide should check for device availability before designing in any of the components included in this document.

Nomenclature

General Design Considerations include system level considerations that the system designer should account for when developing hardware or software products using the 82443LX.

Schematic, Layout and Routing Updates include suggested changes to the current published schematics or layout, including typos, errors, or omissions from the current published documents.

Documentation Changes include suggested changes to the current published design guide not including the above.

Codes Used in Summary Table

Doc: Document change or update that will be or has been implemented

Shaded: This information is either new or modified from the previous version of this document.

NO.	440LX General Design Considerations	
1		Implementing a RESET BUTTON for Desktop Based Systems

NO.	Plans	440LX Schematic, Layout, and Routing Updates
1	Doc	Guidelines to minimize ESD events that may cause loss of CMOS contents.
2	Doc	Correct Strapping for SMC FDC37C932FR Ultra IO Device VBAT Pin

NO.	Plans	440LX Documentation Changes
1	Doc	Section 6.2.18, Ultra IO Support.

440LX General Design Considerations

1. Implementing a RESET BUTTON for Desktop Based Systems

The following should be considered when implementing a RESET BUTTON for desktop based systems:

The system reset button has typically been connected indirectly to the PWROK input of the PIIX4/PIIX4E. This technique will not reset the suspend well logic, which includes the SMBus Host and Slave controllers. To reset the hardware in the suspend well, the reset button should be connected to the RSMRST# input of the PIIX4/PIIX4E. Assertion of RSMRST#, via a reset button, will result in a complete system reset. RSMRST# assertion will cause SUS[A-C]# to assert which results in the deassertion of PWROK if SUS[A-C]# controls the power supply PS-ON control signal. The deassertion of PWROK will cause the PIIX4/PIIX4E to assert PCIRST#, RSTDRV, and CPURST.

440LX Schematic, Layout and Routing Updates

1. Guidelines to Minimize ESD Events that may Cause Loss of CMOS Contents

Recommendations for New Board Designs:

1. Provide a 1uF X5R dielectric, monolithic, ceramic capacitor between the VCCRTC pin of the PIIIX4/PIIX4E and the ground plane. This capacitor's positive connection should not be stubbed off the trace run and must be as close as possible to the PIIIX4/PIIX4E. The cap must be no further than 0.5 inch from the PIIIX4/PIIX4E. If a stub is required, it should be kept to a few mm maximum length. The ground connection should be made through a via to the ground plane, with no or minimal trace between the capacitor pad and the via.
2. Place the battery, 1K ohm series current limit resistor, and the common-cathode isolation diode very close to the PIIIX4/PIIX4E. If this is not possible, place the common-cathode diode and the 1K Ohm resistor as close to the 1uF capacitor as possible. Do not place these components between the capacitor and the PIIIX4. The battery can be placed remotely from the PIIIX4/PIIX4E.
3. On boards that have chassis-intrusion utilizing external logic powered by the VCCRTC pin, place the inverters as close to the common-cathode diode as possible. If this is not possible, keep the trace run near the center of the board.
4. Keep the PIIIX4/PIIX4E VCCRTC trace away from the board edge. If this trace must run from opposite ends of the board, keep the trace run towards the board center, away from the board edge where contact could be made by people and equipment that handle the board.

Recommendations for Existing Board Designs;

1. The effectiveness of adding a 1uF capacitor, as identified above, needs to be determined by examining the routing and placement. For example, placing the cap far from the PIIIX4 reduces its effectiveness.

2. Correct Strapping for SMC FDC37C932FR Ultra IO Device VBAT Pin

When the PIIIX4/PIIX4E internal RTC is used, the SMC Ultra IO device, FDC37C932FR, VBAT pin must be connected to ground through between a 1K and 0 ohm pulldown resistor.

440LX Documentation Changes

1. Design Checklist, section 6.2.18, Ultra IO Support

A new section will be added to section 6.2 as described below.

"When the PIIX4/PIIX4E internal RTC is used, ensure that the VBAT pin of the SMC Ultra IO device, FDC37C932FR, is connected to ground through between a 1K and 0 ohm pulldown resistor. Consult your IO device vendor for implementation guidelines for this or other IO devices."

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